Vishay Siliconix



## **E Series Power MOSFET**



PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.048		
Q <sub>g</sub> max. (nC)	117			
Q <sub>gs</sub> (nC)	26			
Q <sub>gd</sub> (nC)	24			
Configuration	Single			

## FEATURES

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

### APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION			
Package	PowerPAK 10 x 12		
Lead (Pb)-free and halogen-free	SiHK050N65E-T1-GE3		

ABSOLUTE MAXIMUM RATINGS	F (T <sub>C</sub> = 25 °C, unless otherwise	se noted)		
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V <sub>DS</sub>	650	v	
Gate-source voltage	V <sub>GS</sub>	± 30	v	
Continuous drain current ( $T_J = 150 \ ^{\circ}C$ )	$V_{GS} \text{ at } 10 \text{ V} \qquad \frac{T_{C} = 25 \text{ °C}}{T_{C} = 100 \text{ °C}}$	I <sub>D</sub>	45	
	$V_{GS}$ at 10 V $T_C = 100 \text{ °C}$		29	А
Pulsed drain current <sup>a</sup>	I <sub>DM</sub>	129		
Linear derating factor		2.2	W/°C	
Single pulse avalanche energy <sup>b</sup>	E <sub>AS</sub>	311	mJ	
Maximum power dissipation	PD	278	W	
Operating junction and storage temperature ra	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope		dv/dt	100	V/ns
Reverse diode dv/dt <sup>c</sup>	uv/ut	36	V/115	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega,\,I_{AS}$  = 4.7 A
- c.  $I_{SD} \leq I_D, \, di/dt$  = 100 A/µs, starting  $T_J$  = 25  $^\circ C$

RoHS

COMPLIANT HALOGEN



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R <sub>thJA</sub>	-	50	°C/W	
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.45	0/₩	

Notes

a. When mounted on 1" x 1" FR4 board

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		650	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.62	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$		3.0	-	5.0	V
	I <sub>GSS</sub>	,	$V_{GS} = \pm 20 V$		-	± 100	nA
Gate-source leakage		,	V <sub>GS</sub> = ± 30 V	-	-	± 1	μA
	I <sub>DSS</sub>	V <sub>DS</sub> =	= 650 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current		V <sub>DS</sub> = 520 V	$V_{DS} = 520 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$		3	-	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub> = 16 A	-	0.048	0.055	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub>	= 10 V, I <sub>D</sub> = 16 A	-	16	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V,$		-	3992	-	
Output capacitance	C <sub>oss</sub>		$V_{DS} = 100 V,$		181	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 100 KHz		-	2	-	
Effective output capacitance, energy related <sup>a</sup>	$C_{o(er)}$	$V_{DS} = 0$ V to 400 V, $V_{GS} = 0$ V		-	167	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	1119	-	
Total gate charge	Qg			-	78	117	nC
Gate-source charge	Q <sub>gs</sub>	$V_{GS} = 10 V$	$I_D = 16 \text{ A}, V_{DS} = 520 \text{ V}$	-	26	-	
Gate-drain charge	Q <sub>gd</sub>				24	-	1
Turn-on delay time	t <sub>d(on)</sub>		$V_{DD}$ = 520 V, I <sub>D</sub> = 17.3 A, V <sub>GS</sub> = 10 V, R <sub>g</sub> = 10.1 Ω		33	66	- ns
Rise time	t <sub>r</sub>	V <sub>DD</sub> =			27	54	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =			98	196	
Fall time	t <sub>f</sub>			-	11	22	
Gate input resistance	Rg	f = 1 MHz		0.5	1.0	2.0	Ω
Drain-Source Body Diode Characteristic	s	-					
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	45	
Pulsed diode forward current	I <sub>SM</sub>			-	-	129	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 16 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 16 \text{ A},$ di/dt = 100 A/µs, V <sub>R</sub> = 400 V		-	353	706	ns
Reverse recovery charge	Q <sub>rr</sub>			-	4.8	9.6	μC
Reverse recovery current	I <sub>RRM</sub>			-	21.2	-	A



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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

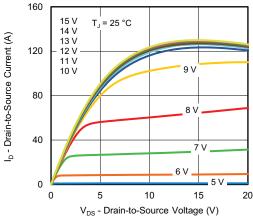


Fig. 1 - Typical Output Characteristics

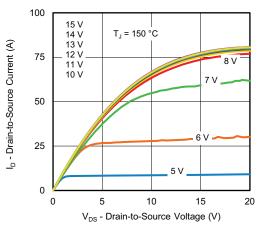


Fig. 2 - Typical Output Characteristics

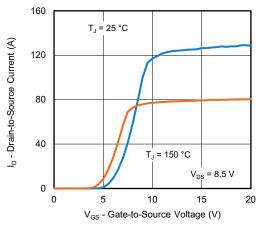


Fig. 3 - Typical Transfer Characteristics

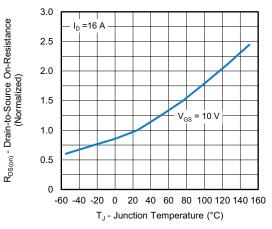


Fig. 4 - Normalized On-Resistance vs. Temperature

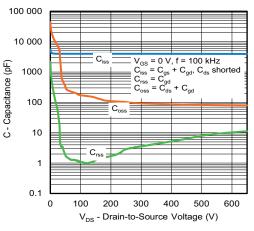
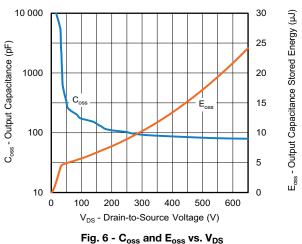


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



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3 For technical questions, contact: hvm@vishay.com Document Number: 92559

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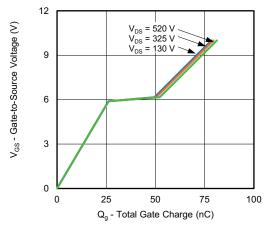


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

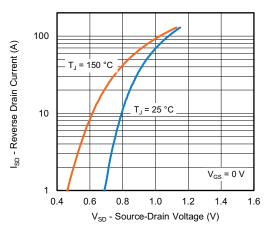


Fig. 8 - Typical Source-Drain Diode Forward Voltage

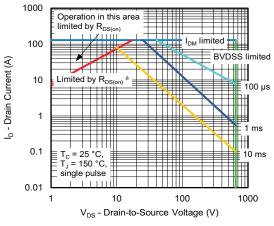


Fig. 9 - Maximum Safe Operating Area

Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

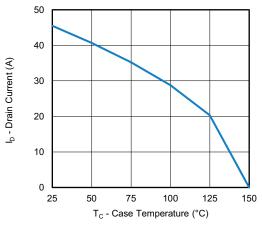


Fig. 10 - Maximum Drain Current vs. Case Temperature

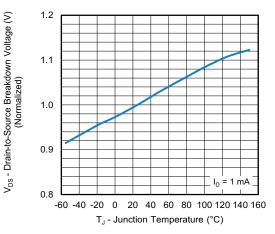


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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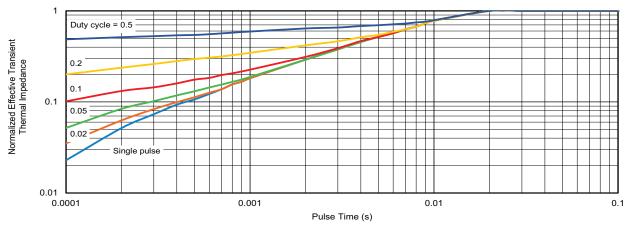


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

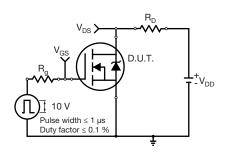


Fig. 13 - Switching Time Test Circuit

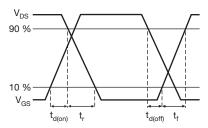


Fig. 14 - Switching Time Waveforms

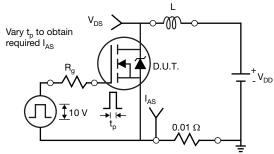


Fig. 15 - Unclamped Inductive Test Circuit

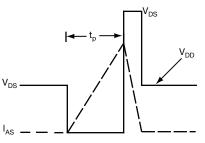


Fig. 16 - Unclamped Inductive Waveforms

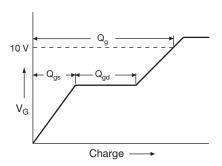


Fig. 17 - Basic Gate Charge Waveform

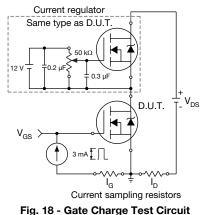


Fig. 18 - Gate Charge Test Circuit

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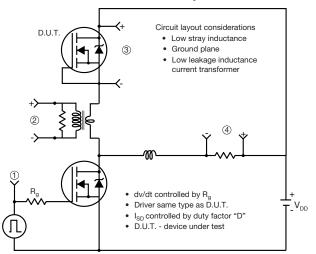
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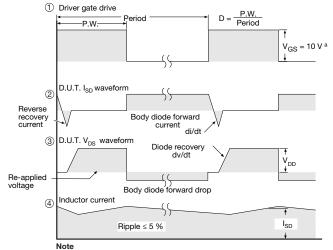
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### Peak Diode Recovery dv/dt Test Circuit





a.  $V_{GS} = 5$  V for logic level devices

Fig. 19 - For N-Channel

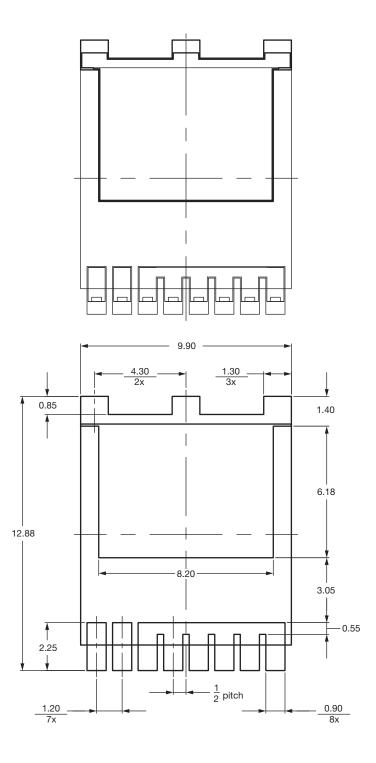
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## **PAD** Pattern



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# Recommended Land Pattern PowerPAK<sup>®</sup> 10 x 12 (TOLL) (High Voltage)



### Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022 DWG: 3013

Revision: 26-Dec-2022

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